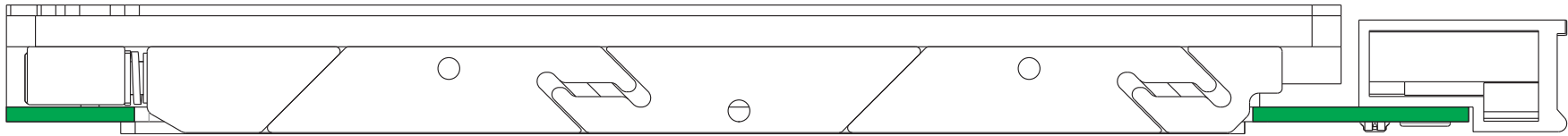
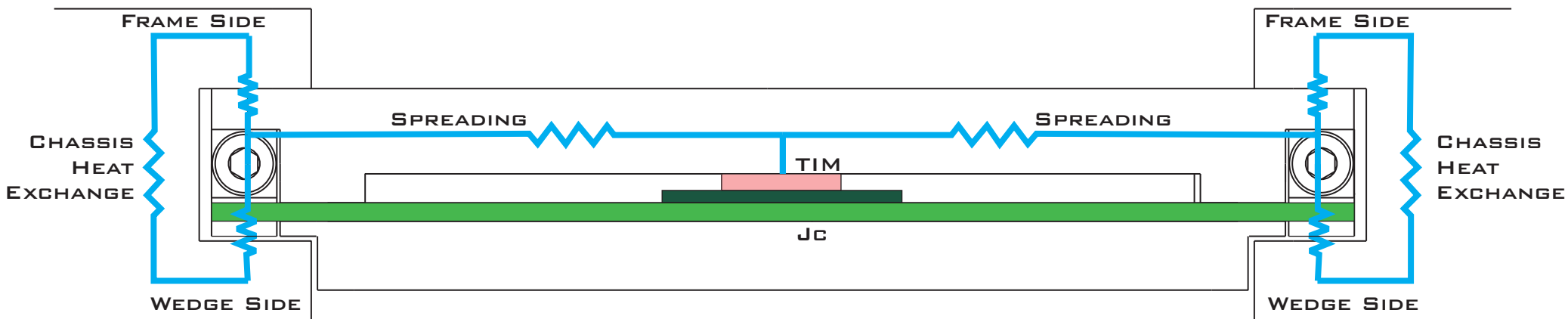


PASS-THRU WEDGE LOCKS



PCB REMOVED FROM COLDWALL THERMAL PATH
CONVECTION FRONT PANEL HOLES REMAIN IN PCB



$$\theta_{(COLDWALL)} = \frac{(\theta_{(WEDGE\ SIDE)} \times (\theta_{(FRAME\ SIDE)}))}{\theta_{(WEDGE\ SIDE)} + \theta_{(FRAME\ SIDE)}}$$

$$\theta_{(COLDWALL)} = \frac{(.76C^{\circ}/W \times (.23C^{\circ}/W))}{(.76C^{\circ}/W + .23C^{\circ}/W)}$$

$$\theta_{(COLDWALL)} = \sim 0.18 C^{\circ}/W \text{ PER EDGE}$$

$$\theta_{(COLDWALL)} = \sim 0.09 C^{\circ}/W$$

THERMAL RESISTANCE VLAUES:

WEDGE SIDE = 0.76C°/W

FRAME SIDE = 0.23C°/W

2 EDGES PER CARD